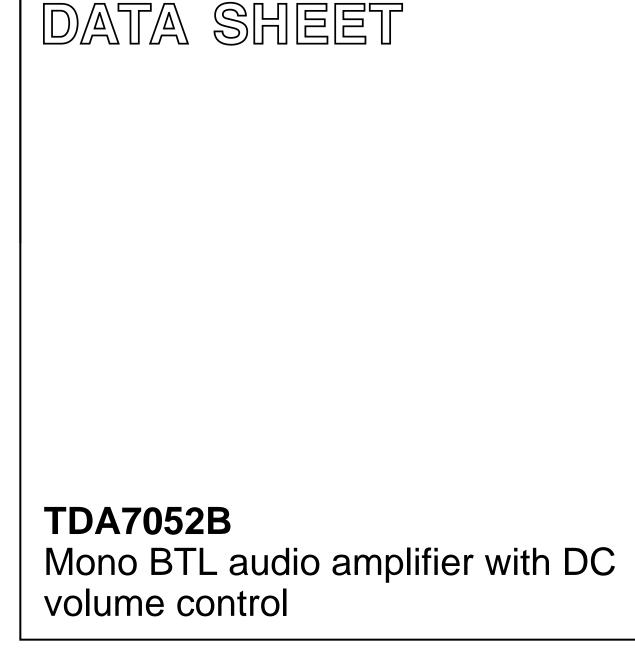
### INTEGRATED CIRCUITS



Preliminary specification Supersedes data of July 1994 File under Integrated Circuits, IC01 1996 May 28



### **TDA7052B**

### FEATURES

- DC volume control
- Few external components
- Mute mode
- Thermal protection
- Short-circuit proof
- No switch-on and switch-off clicks
- · Good overall stability
- Low power consumption
- Low HF radiation
- ESD protected on all pins.

### QUICK REFERENCE DATA

### **GENERAL DESCRIPTION**

The TDA7052B and TDA7052BT are 1 W and 0.5 W mono Bridge-Tied Load (BTL) output amplifiers with DC volume control.

They have been designed for use in TV and monitors, but are also suitable for use in battery-fed portable recorders and radios.

A Missing Current Limiter (MCL) is built in. The MCL circuit is activated when the difference in current between the output terminal of each amplifier exceeds 100 mA (300 mA typ.). This level of 100 mA allows for headphone applications (single-ended).

SYMBOL	PARAMETERS	CONDITIONS	MIN.	TYP.	MAX.	UNIT
VP	supply voltage		4.5	-	18	V
Po	output power	V <sub>P</sub> = 6 V				
	TDA7052B	$R_L = 8 \Omega$	0.9	1.0	-	W
	TDA7052BT	$R_L = 16 \Omega$	0.5	0.55	-	W
G <sub>v(max)</sub>	maximum total voltage gain		39.5	40.5	41.5	dB
φ	gain control		68	73.5	-	dB
I <sub>q(tot)</sub>	total quiescent current	$V_P = 6 V; R_L = \infty$	_	9.2	13	mA
THD	total harmonic distortion					
	TDA7052B	P <sub>O</sub> = 0.5 W	-	0.3	1	%
	TDA7052BT	P <sub>O</sub> = 0.25 W	-	0.3	1	%

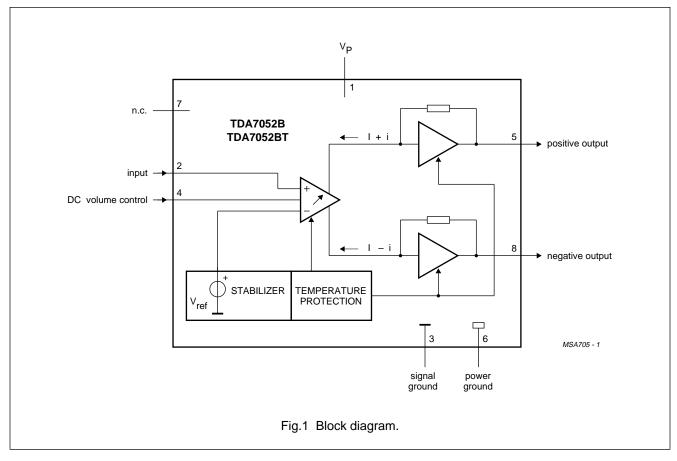
### **ORDERING INFORMATION**

TYPE	PACKAGE				
NUMBER	NAME	DESCRIPTION	VERSION		
TDA7052B	DIP8	plastic dual in-line package; 8 leads (300 mil)	SOT97-1		
TDA7052BT	SO8 plastic small outline package; 8 leads; body width 3.9 mm		SOT96-1		

### Preliminary specification

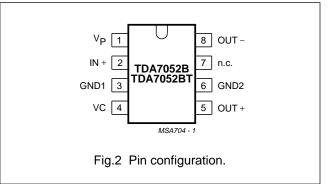
### TDA7052B

### **BLOCK DIAGRAM**



### PINNING

SYMBOL	PIN	DESCRIPTION
V <sub>P</sub>	1	supply voltage
IN+	2	input
GND1	3	signal ground
VC	4	DC volume control
OUT+	5	positive output
GND2	6	power ground
n.c.	7	not connected
OUT-	8	negative output



### FUNCTIONAL DESCRIPTION

The TDA7052B and TDA7052BT are mono BTL output amplifiers with DC volume control which have been designed for use in TV and monitors but are also suitable for use in battery-fed portable recorders and radios.

In conventional DC volume circuits the control or input stage is AC coupled to the output stage via external capacitors to keep the offset voltage low. In the TDA7052B and TDA7052BT the DC volume control stage is integrated into the input stage so that no coupling capacitors are required. With this configuration, a low offset voltage is maintained and the minimum supply voltage remains low.

The BTL principle offers the following advantages:

- · Lower peak value of the supply current
- The frequency of the ripple on the supply voltage is twice the signal frequency.

Consequently, a reduced power supply with smaller capacitors can be used which results in cost reductions. For portable applications there is a trend to decrease the supply voltage, resulting in a reduction of output power at conventional output stages. Using the BTL principle increases the output power. The maximum gain of the amplifier is fixed at 40.5 dB. The DC volume control stage has a logarithmic control characteristic. Therefore, the total gain can be controlled from 40.5 dB to -33 dB. If the DC volume control voltage falls below 0.4 V, the device will switch to the mute mode.

The amplifier is short-circuit proof to ground, V<sub>P</sub> and across the load. Also a thermal protection circuit is implemented. If the crystal temperature rises above +150 °C the gain will be reduced, thereby reducing the output power. Special attention is given to switch-on and switch-off clicks, low HF radiation and a good overall stability.

### **Power dissipation**

Assume for the TDA7052B that V<sub>P</sub> = 6 V; R<sub>L</sub> = 8  $\Omega$ . The maximum sine wave dissipation is 0.9 W. The R<sub>th j-a</sub> of the package is 100 K/W. Therefore T<sub>amb(max)</sub> = 150 - 100 × 0.9 = 60 °C.

Assume for the TDA7052BT that V<sub>P</sub> = 6 V; R<sub>L</sub> = 16  $\Omega$ . The maximum sine wave dissipation is 0.46 W. The R<sub>th j-a</sub> of the package is 155 K/W. Therefore T<sub>amb(max)</sub> = 150 - 155 × 0.46 = 78 °C.

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
VP	supply voltage		_	18	V
V <sub>2, 4</sub>	input voltage pins 2 and 4		_	5	V
I <sub>ORM</sub>	repetitive peak output current		_	1.25	A
I <sub>OSM</sub>	non-repetitive peak output current		_	1.5	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
	TDA7052B		-	1.25	W
	TDA7052BT		_	0.8	W
T <sub>amb</sub>	operating ambient temperature		-40	+85	°C
T <sub>stg</sub>	storage temperature		-55	+150	°C
T <sub>vj</sub>	virtual junction temperature		_	+150	°C
T <sub>sc</sub>	short-circuit time		_	1	h

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient in free air		
	TDA7052B	100	K/W
	TDA7052BT	155	K/W

### CHARACTERISTICS

 $V_P = 6 V$ ;  $V_{DC} = 1.4 V$ ; f = 1 kHz;  $R_L = 8 \Omega$ ;  $T_{amb} = 25 °C$ ; unless otherwise specified (see Fig.13).

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
V <sub>P</sub>	supply voltage		4.5	-	18	V
I <sub>q(tot)</sub>	total quiescent current	note 1; R <sub>L</sub> = ∞	-	9.2	13	mA
Maximum	gain (V <sub>4</sub> ≥ 1.4 V)					
Po	output power	THD = 10%				
	TDA7052B		0.9	1.0	_	W
	TDA7052BT		0.5	0.55	_	W
THD	total harmonic distortion					
	TDA7052B	P <sub>O</sub> = 0.5 W	-	0.3	1	%
	TDA7052BT	P <sub>O</sub> = 0.25 W	-	0.3	1	%
G <sub>v(max)</sub>	maximum total voltage gain		39.5	40.5	41.5	dB
VI	input signal handling (RMS value)	$G_{v(max)} = 0 \text{ dB}; \text{ THD} < 1\%$	1.0	-	-	V
V <sub>no</sub>	noise output voltage (RMS value)	note 2; f = 500 kHz	-	210	-	μV
В	bandwidth	at –1 dB	_	0.02 to 300	-	kHz
SVRR	supply voltage ripple rejection	note 3	34	38	-	dB
$ \Delta V_{O} $	DC output offset voltage	V <sub>8</sub> - V <sub>5</sub>	-	0	200	mV
ZI	input impedance (pin 3)		15	20	25	kΩ
Mute posi	tion	•		•	•	•
V <sub>O</sub>	output voltage in mute position	note 4; $V_4 = 0.4 \text{ V} \pm 30 \text{ mV}$ ; $V_1 = 1.0 \text{ V}$	-	30	40	μV
DC volum	e control; note 5					
φ	gain control		68	73.5	-	dB
I <sub>4</sub>	control current	$V_4 = 0 V$	20	25	30	μA

#### Notes

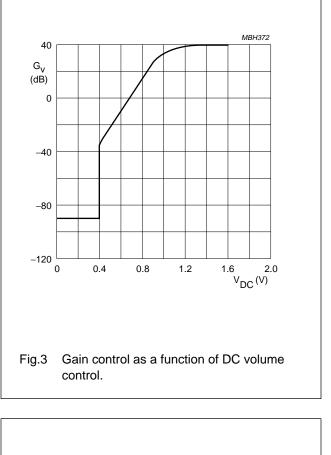
1. With a load connected to the outputs the quiescent current will increase, the maximum value of this increase being equal to the DC output offset voltage divided by R<sub>L</sub>.

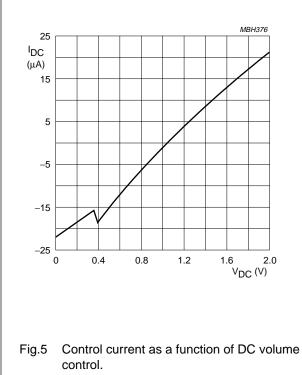
2. The noise output voltage (RMS value) at f = 500 kHz is measured with  $R_S = 0 \Omega$  and B = 5 kHz.

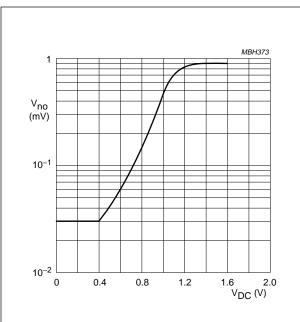
3. The ripple rejection is measured with  $R_S = 0 \Omega$  and f = 100 Hz to 10 kHz. The ripple voltage V<sub>R</sub> of 200 mV (RMS value) is applied to the positive supply rail.

- 4. The noise output voltage (RMS value) is measured with  $R_S = 5 k\Omega$  unweighted.
- 5. The DC volume control can be configured in several ways. Two possible circuits are shown in Figs 14 and 15. The circuits at the volume control pin will influence the switch-on and switch-off behaviour and the maximum voltage gain.

### TDA7052B

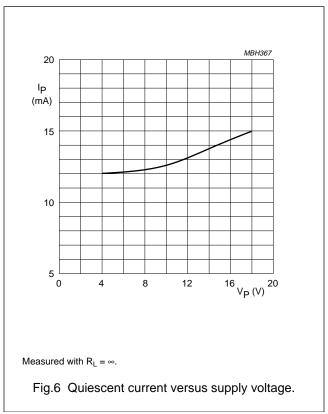


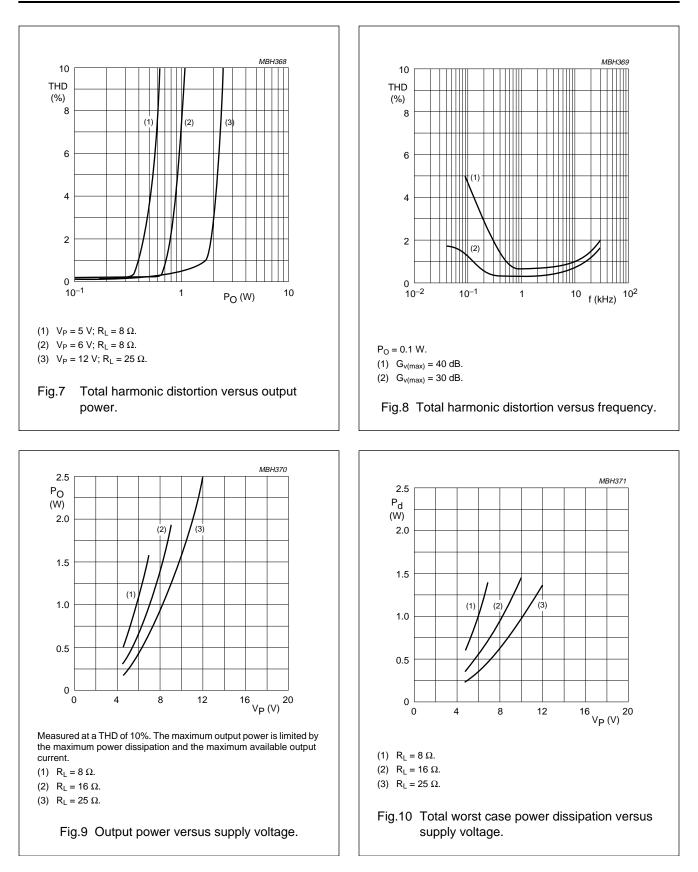




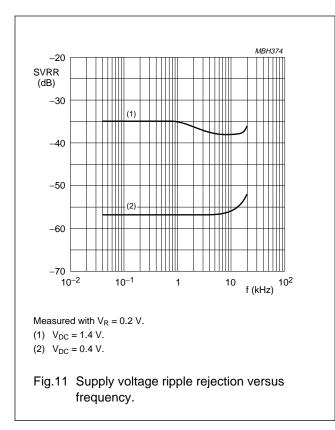
Measured with  $R_S = 5 k\Omega$  unweighted. Frequency range is 22 Hz to 22 kHz.

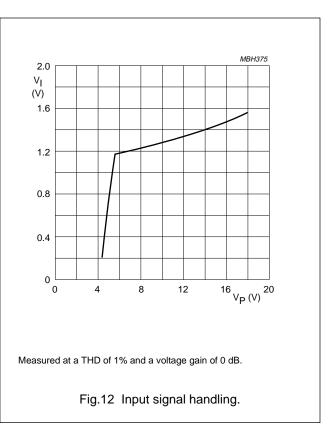
Fig.4 Noise output voltage as a function of DC volume control.





### TDA7052B



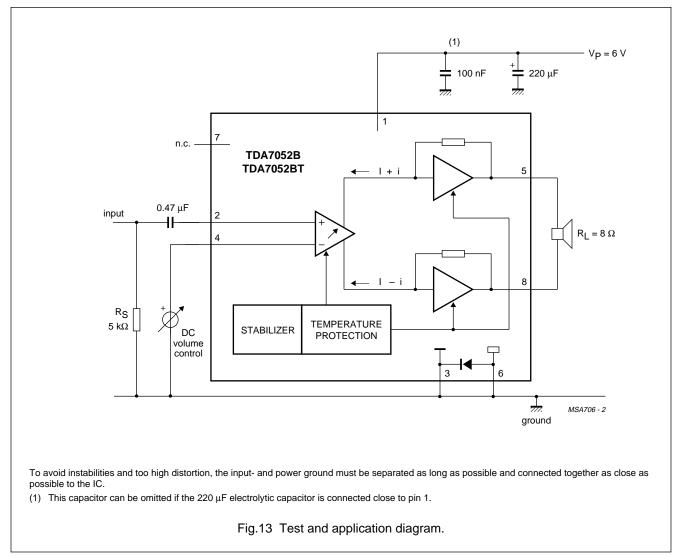


### QUALITY SPECIFICATION

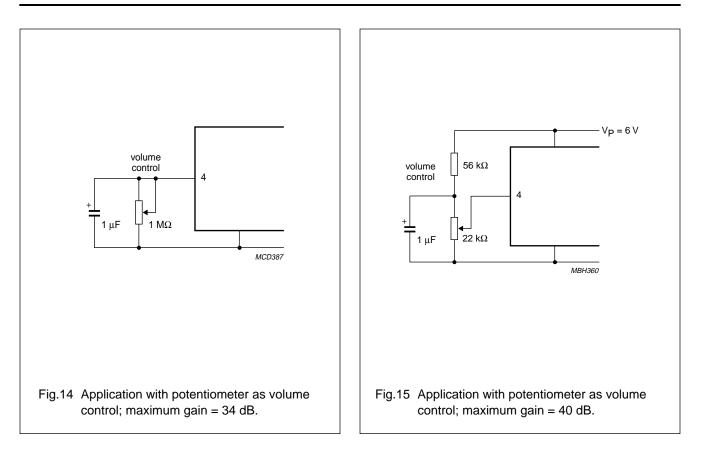
In accordance with "SNW-FQ-611E", if this type is used as an audio amplifier.

### TDA7052B

### **TEST AND APPLICATION INFORMATION**



For single-end application the output peak current may not exceed 100 mA; at higher output currents the short circuit protection (MCL) will be activated.



OUTLINE

VERSION

SOT97-1

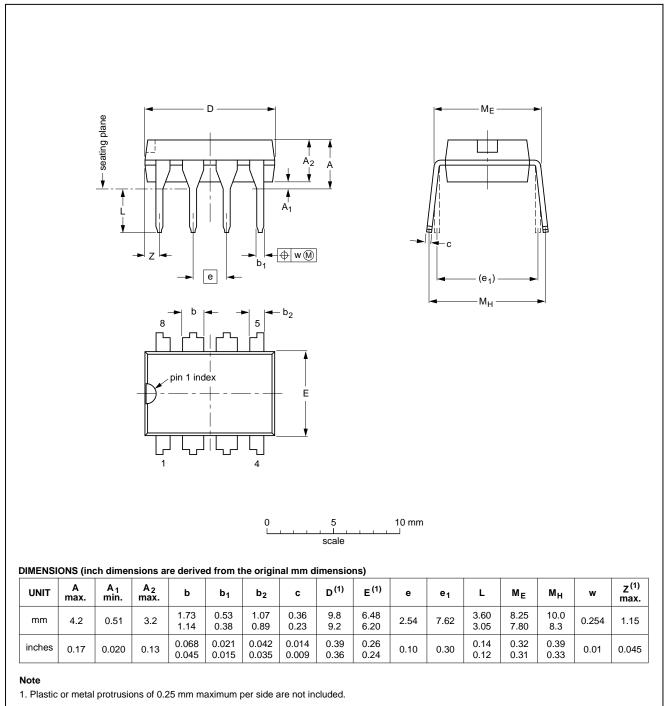
IEC

050G01

## Mono BTL audio amplifier with DC volume control

### PACKAGE OUTLINES

### DIP8: plastic dual in-line package; 8 leads (300 mil)



TDA7052B

SOT97-1

EIAJ

EUROPEAN

PROJECTION

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ISSUE DATE

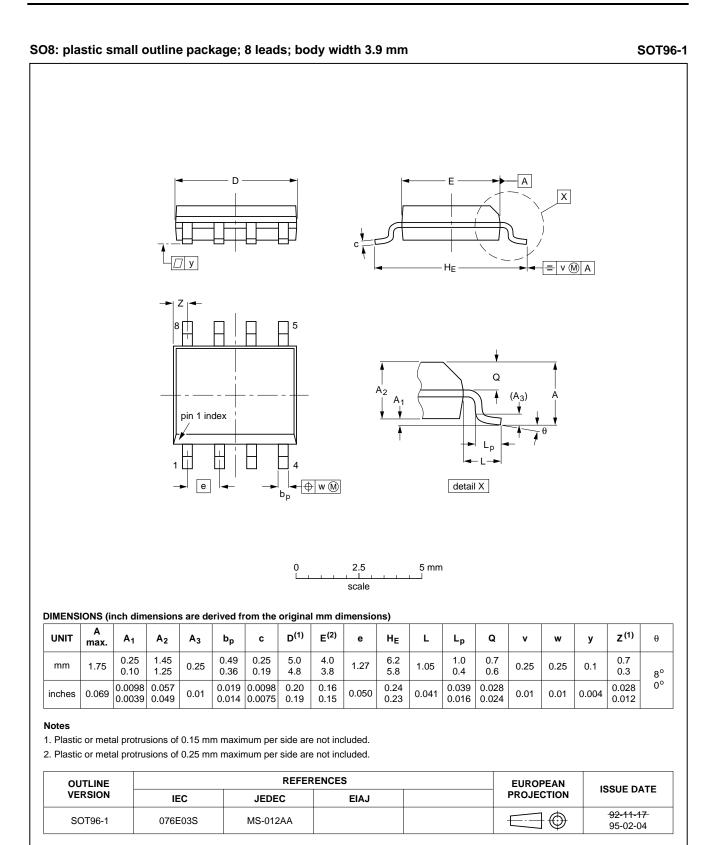
92-11-17

95-02-04

REFERENCES

JEDEC

MO-001AN



### TDA7052B

### SOLDERING

#### Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

### DIP

#### SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ( $T_{stg\,max}$ ). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

### REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

### SO

### REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement. Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

#### WAVE SOLDERING

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

### REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

TDA7052B

### DEFINITIONS

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.				
Application information				
Where application information is given, it is advisory and does not form part of the specification.				

### LIFE SUPPORT APPLICATIONS

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Tel. +60 3 750 5214, Fax. +60 3 757 4880 Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905 Tel. +1 800 234 7381, Fax. +1 708 296 8556

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB, Tel. +31 40 27 83749, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND, Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO, Tel. +47 22 74 8000, Fax. +47 22 74 8341

Philippines: Philips Semiconductors Philippines Inc., 106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI, Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474 Poland: Ul. Lukiska 10, PL 04-123 WARSZAWA,

Tel. +48 22 612 2831, Fax. +48 22 612 2327

Portugal: see Spain

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Russia: Philips Russia, UI. Usatcheva 35A, 119048 MOSCOW, Tel. +7 095 926 5361, Fax. +7 095 564 8323

Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231, Tel. +65 350 2538, Fax. +65 251 6500

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South America: Rua do Rocio 220 - 5th floor, Suite 51, CEP: 04552-903-SÃO PAULO-SP, Brazil, P.O. Box 7383 (01064-970), Tel. +55 11 821 2333, Fax. +55 11 829 1849

**Spain:** Balmes 22, 08007 BARCELONA, Tel. +34 3 301 6312, Fax. +34 3 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM, Tel. +46 8 632 2000, Fax. +46 8 632 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH, Tel. +41 1 488 2686, Fax. +41 1 481 7730

Taiwan: PHILIPS TAIWAN Ltd., 23-30F, 66, Chung Hsiao West Road, Sec. 1, P.O. Box 22978, TAIPEI 100, Tel. +886 2 382 4443, Fax. +886 2 382 4444

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,

209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260, Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL, Tel. +90 212 279 2770, Fax. +90 212 282 6707

Ukraine: PHILIPS UKRAINE, 2A Akademika Koroleva str., Office 165, 252148 KIEV, Tel. +380 44 476 0297/1642, Fax. +380 44 476 6991 United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,

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